## How to Monitor Die Temperature TI Precision Labs – Temperature Sensors

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## **Why Monitor Die Temperature?**

### **Protect Systems**

### **Optimize Performance**







## How to Monitor Die Temperature

Integrated sensor	Integrated Thermal Diode	External Sensor
	Processor or ASIC	System Board
	Built-In Thermal Transistor, diode	Processor or ASIC External Temperature Sensor



### Die Temperature Monitoring Integrated Thermal Diode

Integrated PNP Transistorconnected Configuration





If  $\beta$ >>> then  $I_C \approx I_E$ 

- T = Temperature
- q = charge of electron
- $V_{EB}$  = Emitter-Base Voltage
- $\eta$  = ideality factor
- k = Boltzmann Constant
- $I_{\rm C}$  = Collector Current
- $I_{E}$  = Emitter Current
- $\beta$  = Gain of the transistor



### Integrated Thermal Diode Sources of Error

### Thermal Diode error sources:

- η -factor Variation
- β Variation
- Series Resistance
- Noise Injection





### Die Temperature Monitoring External Temperature Sensor





### Die Temperature Monitoring Temperature Sensor Design Guidelines

### **External Temperature Sensor**

### **Integrated Thermal Diode**





## Thank you!

## To find more temperature sensor resources and products visit ti.com/temperature



## How to Monitor Die Temperature TI Precision Labs – Temperature Sensors

Quiz





- 1. In which devices is die temperature monitoring important?
  - a) CPUs and GPUs
  - b) ASICs and CPUs
  - c) FPGAs and GPUs
  - d) All of the above
- 2. What is **not** a device used for measuring die temperature
  - a) Integrated thermal diodes
  - b) External temperature sensors
  - c) Thermal ferrite beads
  - d) Integrated temperature sensors



- 3. What source of error is caused by PCB traces or cabling when using the integrated thermal diode method?
  - Series resistance a)
  - b) Noise injection
  - $\eta$  -factor variation C)
  - $\beta$  variation d)
- 4. What source of error is trying to be avoided by using shielded twisted pair cables?
  - a) Series resistance
  - b) Noise injection
  - $\eta$  -factor variation C)
  - $\beta$  variation d)



- 5. What factor is not used by remote temperature sensors to calculate temperature?
  - η -factor a)
  - Boltzmann constant b)
  - Power consumption of the remote junction C)
  - Base Emitter Voltage d)
- 6. What is an important design guideline when using an external temperature sensor?
  - a) Differential pair routing
  - Shield twisted pair cabling b)
  - Sharing a solid ground plane C)
  - Both a and b d)



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# Answers

- 1. In which devices is die temperature monitoring important?
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  - c) FPGAs and GPUs
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- 2. What is **not** a method of measure die temperature
  - a) Integrated thermal diodes
  - b) External temperature sensors
  - c) Thermal ferrite beads
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- 3. What source of error is caused by PCB traces or cabling when using the integrated thermal diode method?
  - Series resistance a)
  - b) Noise injection
  - $\eta$  -factor variation C)
  - $\beta$  variation d)
- 4. Shielded twisted pair cables are used to avoid what source of error?
  - Series resistance a)
  - Noise injection b)
  - $\eta$  -factor variation C)
  - $\beta$  variation d)



- 5. What is not used by remote temperature sensors to calculate temperature?
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